

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

CLAIMS

1. (Currently Amended) A method of coating a substrate-(12), ~~the said~~ method being the type comprising:

- placing ~~the said~~ substrate-(12) in an enclosure-(14) under vacuum;
- forming a gas by evaporating a component that is liquid at atmospheric pressure and at ambient temperature;
- introducing ~~the said~~ gas into ~~the said~~ enclosure-(14); and
- decomposing ~~the said~~ gas;

~~the said~~ method being characterised by introducing a complementary gas into ~~the said~~ enclosure-(14) for the purpose of reacting with ~~the said~~ decomposed gas so as to form, on ~~the said~~ substrate-(12), at least one thin layer, referred to as thin layer A.

2. (Currently Amended) ~~A~~The method of coating a substrate-(12) according to claim 1, in which ~~the said~~ component-(28) is made up of organic and inorganic groups, e.g. of silicone.

3. (Currently Amended) ~~A~~The method of coating a substrate-(12) according to claim 1 or claim 2, in which ~~the said~~ complementary gas is monomolecular up to at least 90%.

4. (Currently Amended) AThe method of coating a substrate-(12) according to claim 3, in which the said complementary gas comprises, for the most part, either di-oxygen, or argon, or dinitrogen, or dihydrogen, or acetylene.

5. (Currently Amended) AThe method of coating a substrate-(12) according to any one of claims 1 to 4 claim 1, in which the said gas is decomposed with the help of electric plasma-creation means-(40).

6. (Currently Amended) AThe method of coating a substrate-(12) according to any one of claims 1 to 5 claim 1, further comprising a step of forming another thin layer, referred to as a thin layer B, on the said substrate, by vacuum deposition after or before forming the said thin layer A.

7. (Currently Amended) AThe method of coating a substrate according to claim 6, in which said thin layers A and B are formed without extracting the said substrate-(12) from the said enclosure-(14) between forming each layer.

8. (Currently Amended) AThe method of getting coating a substrate-(12) according to claim 6or claim 7, in which the said thin layer A is formed after the said thin layer B in such a manner as to cover said thin layer B, in particular in order to provide it with mechanical and/or chemical protection.

9. (Currently Amended) AThe method of coating a substrate-(12) according to claim 6or claim 7, in which the said thin layer B is formed after the said thin layer A in such a manner that said thin layer A encourages smoothing the said substrate and/or bonding the said thin layer B.

10. (Currently Amended) A-The method of coating a substrate-(12) according to-any one of claims 6 to 9 claim 6, in which the-said thin layer B is a layer of metalization.

11. (Currently Amended) AThe method of coating a substrate-(12) according to claim 10, in which the-said layer of metalization is formed by evaporating a solid component.

12. (Currently Amended) A-The method of coating a substrate-(12) according to claim 10, in which the-said layer of metalization is formed by evaporating an organometallic component that is in the liquid phase at ambient temperature and at atmospheric pressure.

13. (Currently Amended) A method of forming a colouredcolored film on a substrate-(12), thesaid method being the type in which at least two thin layers having different refractive indices are deposited on thesaid substrate, thesaid method being characterized in that at least one of the-said thin layers is obtained by a coating method according to-any one of claims 1 to 5 claim 1.

14. (Currently Amended) A The device for implementing a method of coating a substrate (12) according to ~~any one of claims 1 to 12~~ claim 1, the said device being characterised in ~~that it comprises~~ comprising:

- an enclosure (14) for housing the said substrate (12);
- the a tank (26) external to the said enclosure (14) for containing a liquid component (28);
  - first admission means (18) for admitting a gas into the said enclosure and comprising means (24) for connecting the said enclosure (14) to a portion of the said tank (26) containing a vapourvapor phase of the gas-forming liquid;
  - means (40) for decomposing the said gas; and
  - second admission means (32) for admitting a complementary gas for reacting with the said decomposed gas.

15. (Currently Amended) A The coating device (10) according to claim 14, in which the said first admission means (18, 32) include means (22, 36) for adjusting the admission flow rate of the said gas.

16. (Currently Amended) A The coating device according to claim 14 or claim 15, further comprising means (16) for creating a vacuum in the said enclosure (14).

17. (Currently Amended) A The coating device according to ~~any one of claims 14 to 16~~ claim 14, in which the gas-decomposition means are electric means (40) for generating a plasma inside the said enclosure (14) from the said gas.

18.(New) The method of coating a substrate according to claim 2, in which said complementary gas is monomolecular up to at least 90%.

19. (New) The method of coating a substrate according to claim 2, in which said gas is decomposed with the help of electric plasma-creation means.

20. (New) The method of coating a substrate according to claim 3, in which said gas is decomposed with the help of electric plasma-creation means.

21. (New) The method of coating a substrate according to claim 4, in which said gas is decomposed with the help of electric plasma-creation means.

22. (New) A method of coating a substrate, said method comprising the steps of:  
placing said substrate in an enclosure under vacuum;  
forming a gas by evaporating a component that is liquid at atmospheric pressure and at ambient temperature;  
introducing said gas into said enclosure;  
decomposing said gas; and  
introducing a complementary gas into said enclosure for the purpose of reacting with a decomposed gas so as to form, on said substrate, at least one first thin layer.

23. (New) The method of coating a substrate according to claim 22, further comprising a step of forming at least one second thin layer on said substrate, by vacuum deposition after or before forming said at least one first thin layer.

24. (New) The method of coating a substrate according to claim 2, in which said at least one third thin layer is formed to cover said at least one second thin layer, in particular in order to provide it with mechanical and/or chemical protection.

25. (New) The method of coating a substrate according to claim 1, wherein said method further comprises the step of depositing at least two thin layers having different refractive indices on said substrate to provide a colored film on said substrate.

26. (New) A system for coating a substrate, said system comprising:  
an enclosure for housing said substrate;  
a tank in fluid communication with said enclosure for containing a liquid and for providing a gas from said liquid to said enclosure;  
means for decomposing said gas after it is received in said enclosure from said tank; and  
a complementary gas source in fluid communication with said enclosure for providing a complementary gas to said enclosure for reacting with said decomposed gas.

27. (New) The system according to claim 26, wherein said means for decomposing said gas comprises electric means for generating a plasma inside said enclosure from said gas.